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U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	SubClass	Filing Date If Appropriate
MOB	5,741,579	4/21/98	Nishizawa			

FOREIGN PATENT DOCUMENTS

	Document Number	Date of Publication	Country	Class	SubClass	Translation	
						Yes	No
MOB	2061093 ✓	8/15/92	CA			X	
MOB	0 499 585 ✓	8/19/92	EPO (English Abstract Attached)			X	
MOB	0 528 606 ✓	2/24/93	EPO				
MOB	0 790 762 ✓	8/2/97	EPO				
MOB	0 928 027 ✓	7/7/99	EPO				
MOB	56-837	1/7/81	JP (English Abstract Attached)			X	
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OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

MOB	Sasaski, Tomiya, et al., "Development of Sheet Type Thermal Conductive Compound Using Ain," Proceedings of the (Japan) International Electronic Manufacturing Technology Symposium, U.S., New York, IEEE, 12/4/1995, pp. 236-239, XP000686771
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